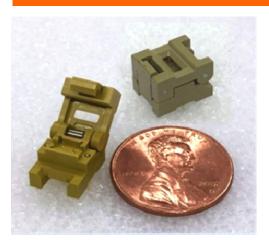


Microminiture Package Sockets

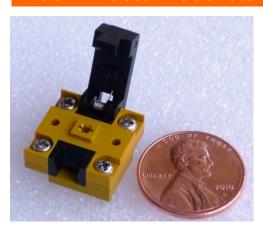
1. Full Custom Sockets



Specific Spec Focus Best Suited to Unique MEMS or Sensor Packages

- ◆ Full Machined
- ◆ Clam Shell Type
- ◆ Spring Probe Contact
- ◆ Contact Pitch: 0.3mm or Wider
- ◆ PCB Mounting Method : TH or CSMT

2. Semi-Custom Sockets



Specifications and Budget Considered

- ◆ Utilize Existing Socket Components
- ♦ Clam Shell Type
- ◆ Spring Probe Contact
- ◆ Contact Pitch: 0.3mm or Wider
- ◆ PCB Mounting Method: TH or CSMT

3. Standard Molded Sockets



Mass Production Application

- Utilize Existing Socket Components
- ◆ Clam Shell Type
- ◆ Spring Probe Contact
- ◆ Contact Pitch : 0.3mm or Wider
- ◆ PCB Mounting Method: TH or CSMT

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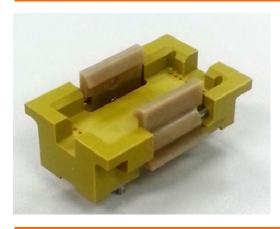
MEMS Microphone Sockets



Wide Opening Top Sockets Best Suited to MEMS Microphone

- ♦ Open Top Type
- ♦ Stamped Contact
- ◆ Contact Pitch : 0.6mm or Wider
- ◆ Solder Tail Pitch: 1.2mm or Wider
- ◆ Through Hole Mount Design

MEMS Mirror Sockets



Wide Angle Clearance Sockets Best Suited to MEMS Mirror Devices

- ◆ Butterfly Type
- ♦ Spring Probe Contact
- ◆ Contact Pitch: 0.6mm or Wider
- ◆ Through Hole Mount Design
- ♦ Opening Angle at Center: ±80 x ±50°

Bare Die Sockets



Bare Die Sockets Enhanced Operation Efficiency

- ♦ Open Top Type
- ♦ Stamped Contact
- ◆ Contact Pitch : 0.35mm or Wider
- ♦ Solder Tail Pitch : 0.7mm or Wider
- ◆ Through Hole Mount Design
- ♦ Opening Angle at Center: ±90 x ±60

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